

POLISHING METHOD AND POLISHING APPARATUS

ABSTRACT OF THE DISCLOSURE

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A polishing method able to easily flatten unevenness
formed on the surface of a film to be polished and able
to efficiently polish the film flat while suppressing
damage to an interlayer insulating film below the film,
10 comprising, when polishing an object having a film such
as an interconnection layer formed burying
interconnection grooves formed in an insulating film of a
substrate, supplying a polishing solution over the
surface to be polished at least substantially parallel to
15 the surface to preferentially remove by polishing the
projecting portions of the film and flatten the surface
by the shear stress of the processing solution or
arranging a cathode member facing the surface and
supplying an electrolytic solution containing a chelating
20 agent between the surface and cathode member while
supplying voltage between the film and the cathode member
to preferentially remove by polishing the projecting
portions of the film and flatten the surface by the shear
stress of the electrolytic solution, and a polishing
25 apparatus using the same.